

ABSTRACT

A laminate multilayer ball-grid-array package is suitable for millimeter-wave circuits. The frequency bandwidth of the package is DC to 40 GHz. The package is made using laminate circuit board materials to match the temperature expansion coefficients of the package to the host PCB. Electrical connection between the package and the host PCB on which the package is mounted is achieved using ball-grid-array technology. The package can be sealed, covered, or encapsulated, and is suitable for high-volume production.

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